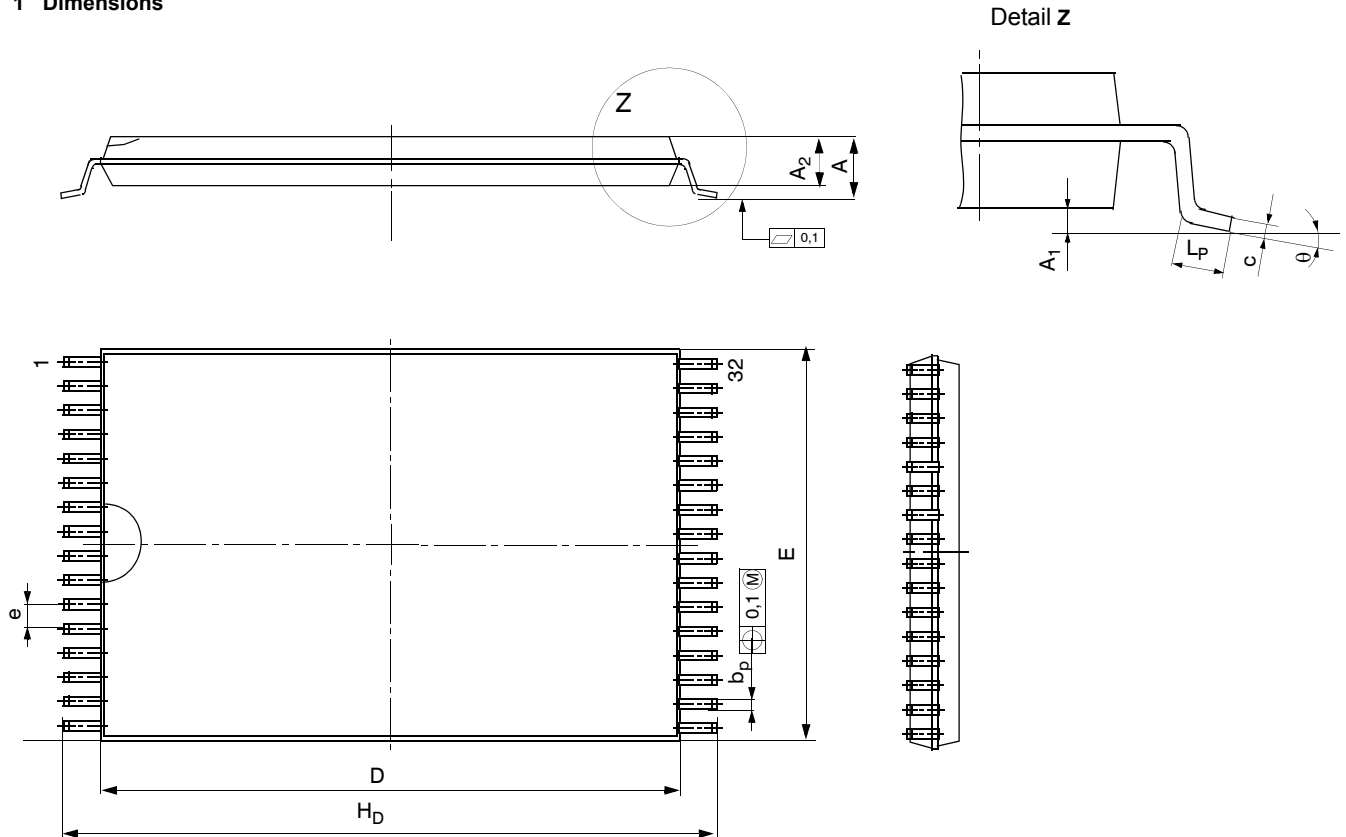


	Package TSOP32 (l/8x13,4)	MDS 768
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Dimensions in millimetres

1 Dimensions



Dimensions of Sub-Group B1	
$A_{\max}$	1,20
$b_{P\min}$	0,17
$b_{P\max}$	0,27
e_{nom}	0,50
$H_{D\min}$	13,20
$H_{D\max}$	13,60
$L_{P\min}$	0,50

- 2 Weight** $\leq 0,3 \text{ g}$
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** FeNi-Alloy or Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** Z-bends

Dimensions of Sub-Group C1	
$A_{\min}$	—
$A_{1\min}$	0,05
$A_{1\max}$	0,15
$A_{2\min}$	0,90
$A_{2\max}$	1,05
$c_{\min}$	0,10
$c_{\max}$	0,21
$D_{\min}^*$	11,70
$D_{\max}^*$	11,90
$E_{\min}^*$	7,90
$E_{\max}^*$	8,10
$\theta_{\min}$	0°
$\theta_{\max}$	5°

* without mold-flash

Zentrum Mikroelektronik Dresden		
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